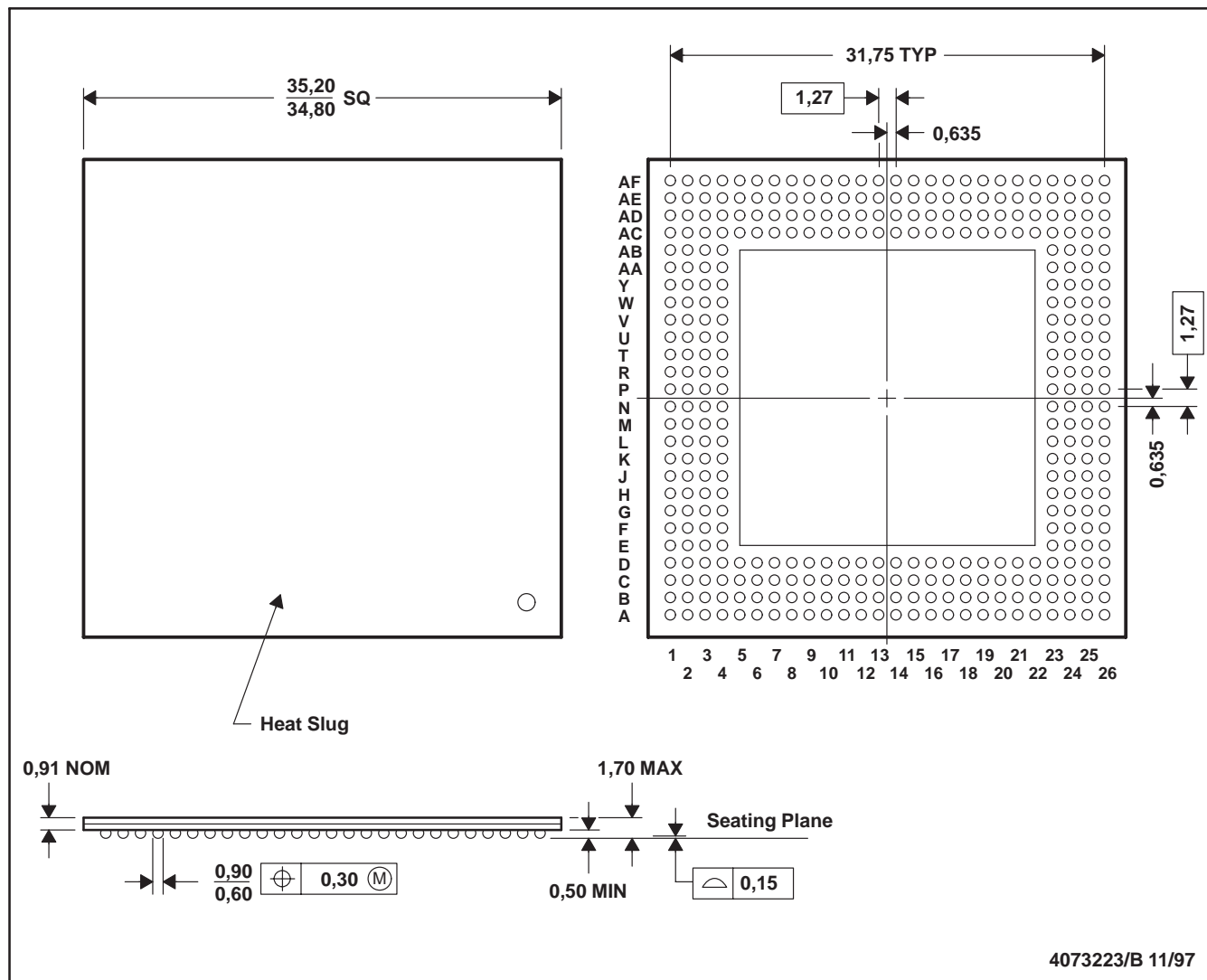


GGP (S-PBGA-N352)

PLASTIC BALL GRID ARRAY (CAVITY DOWN)



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Thermally enhanced plastic package with metal heat slug (HSL).

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